



PRODUCT INFORMATION

Customer :	
Device :	Device ID :
Die Size :	Water Material :
Package Type:	No. of Wires :

18L SOIC WB

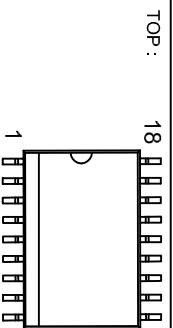
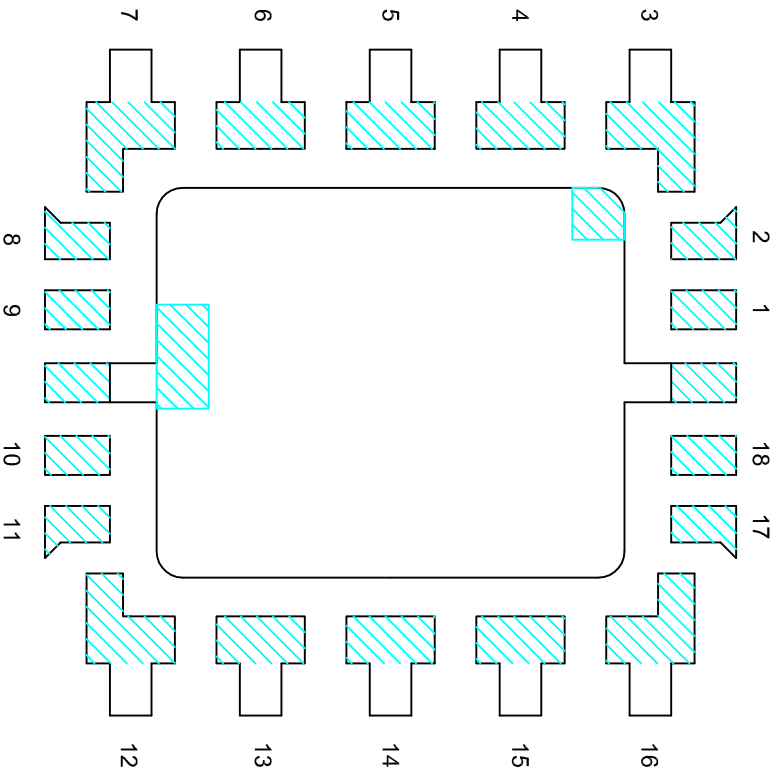
MATERIAL INFORMATION

Leadframe :	Pad Size :
Epoxy :	Wire size :
Molding Compound :	Lead Finish :

A 194 with selective Ag

150X180 mils

MARKING INSTRUCTION



BONDING DIAGRAM NO.

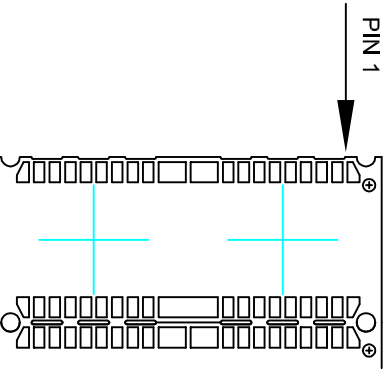
REF. BONDING DIAGRAM NO.

SCALE

not to scale

DRAWN BY: _____ REVIEWED BY: _____

SPECIAL INSTRUCTIONS:



LEADFRAME ORIENTATION

REVISION NO.		APPROVALS		
REV. #	DESCRIPTION	PCN #	DEPT	DATE
			CUST	
			QSM	
			QC	
			MFG	